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U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM 10054001	FILING DATE 01/19/2002	CLASS 257	SUBCLASS 2844	GAU 2844	EXAMINER D
<b>**APPLICANTS:</b> Lin Mou-Shiung; Lee Jin-Yuan; Huang Ching-Cheng;					
<b>**CONTINUING DATA VERIFIED:</b>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b>					
PG-PUB DO NOT PUBLISH <input checked="" type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO MEG01-013	
TITLE : Thin film semiconductor package and method of fabrication					

U.S. DEPT. OF COMM./PAT & TM-PTO-436L (Rev. 12-94)

<b>NOTICE OF ALLOWANCE MAILED</b>		Assistant Examiner	<b>CLAIMS ALLOWED</b>	
			Total Claims	Print Claim for O.G.
<b>ISSUE FEE</b>		Primary Examiner	<b>DRAWING</b>	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		<b>PREPARED FOR ISSUE</b>	Application Examiner	
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